## FLIP - STATION

FLIP- -STATION

MICRO ASSEMBLY

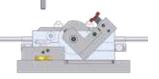
The Tresky **DIE FLIP** - **STATION** is designed to minimize the mechanical stress on the Chip to avoid any damage. The soft flipping of the die upside down is gently controlled and can be activated manually or automatically. An exchangeable tip and support plate allows to handle a wide range of die sizes (down to 0.250mm).

The adjustable speed and height gives you the most possible flexibility to flip a die.

Place component onto the flipper pedestal



Picked component flippes automatically



Flipper arm moves automatically towards pedestal

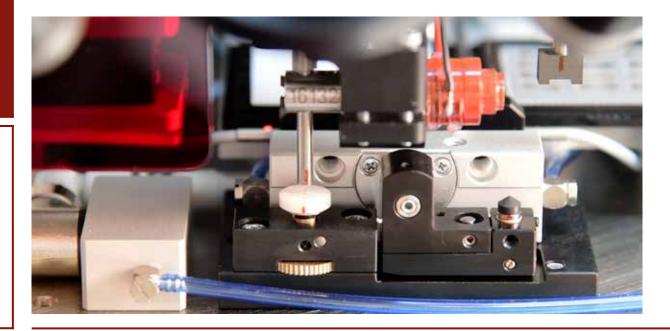


Pick filipped component from flip station

Automatic pick-up of the component



All **T-SOOO SERIES** models can be upgraded with the die flip-station.





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